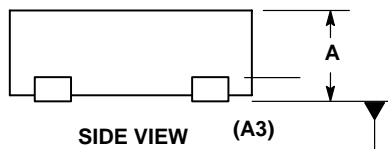
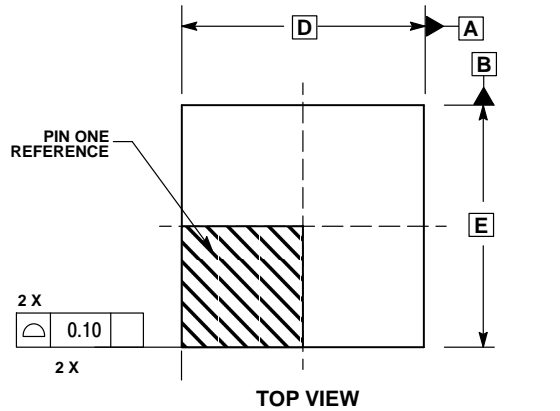




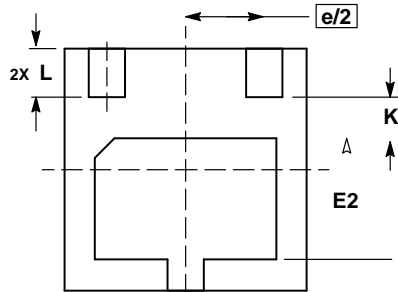
WDFN3 2x2, 1.3P
CASE 506AU
ISSUE A

DATE 18 AUG 2016

SCALE 4:1



D2



	MILLIMETERS			
	3X MIN	NOM	MAX	MIN
A1	0.70	0.75	0.80	0.28
A	0.00	0.20 REF	0.05	0.000
b	0.25	0.30	0.35	0.010
D	1.40	2.00 BSC	1.60	0.055
D2	1.50	1.50	1.60	0.055
E	2.00 BSC	2.00	1.10	0.035
E2	0.90	1.00	1.10	0.035

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

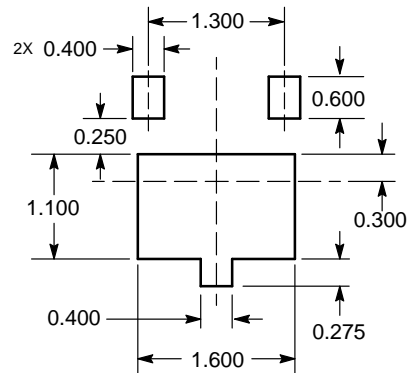
	NOM	MAX
	0.030	0.031
	0.008 REF	0.002
	0.012	0.014
	0.079 BSC	
	0.059	0.063
	0.079 BSC	
	0.039	0.043
e	1.30 BSC	0.051 BSC
K	0.35 REF	0.014 REF
L	0.35	0.40
	0.45	0.014
	0.016	0.018

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.